## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Schwartz et al. PLICANT(s):

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EXAMINER: Cosimano, E.

TITLE:

SECURE POSTAGE PAYMENT SYSTEM AND METHOD

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Commissioner of Patents Washington, D.C. 20231

GROUP 3600

INFORMATION DISCLOSURE STATEMENT (37 C.F.R. \$1.97(c)(1)/(e)(1))

Sir:

This Information Disclosure Statement is being filed pursuant to 37 C.F.R. §1.97(c) before the mailing date of any of a final action under §1.113, a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application.

This Information Disclosure Statement asserts the statement as specified in 37 C.F.R. 1.97(e)(1), that each item of information contained in this information disclosure statement was first cited in any communication from the foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

This application has a corresponding Canadian Patent Application No. 2,225,443. The reference disclosed herein was cited by the Canadian Patent Office in a communication dated December 11, 2002.

The following information is being disclosed to the Patent and Trademark Office as information that may be material to the examination of the above-identified patent application.

U.S. Patent No. 4,855,920

A copy of this reference is enclosed together with a Form PTO-1449 for the Examiner's use.

The Commissioner is hereby authorized to charge payment for any fees associated with this communication or credit any over payment to Deposit Account No. 16-1350.

Respectfully submitted,

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## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date indicated below as first class mail in an envelope address to the Commissioner of Patents, Washington, D.C. 20231.

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